

Electronic Patent Application Fee Transmittal

Application Number:	10554855
Filing Date:	
Title of Invention:	Brittle substrate cutting system and brittle substrate cutting method
First Named Inventor/Applicant Name:	Kenji Otoda
Filer:	Howard I. Sobelman/Julie Eslick
Attorney Docket Number:	49288.1600

Filed as Small Entity

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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Late filing fee for oath or declaration	2051	1	65	65
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Petition:

Patent-Appeals-and-Interference:

Post-Allowance-and-Post-Issuance:

Extension-of-Time:

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				65